

KINGKA TECH INDUSTRIAL LIMITED

-Skived fin technology



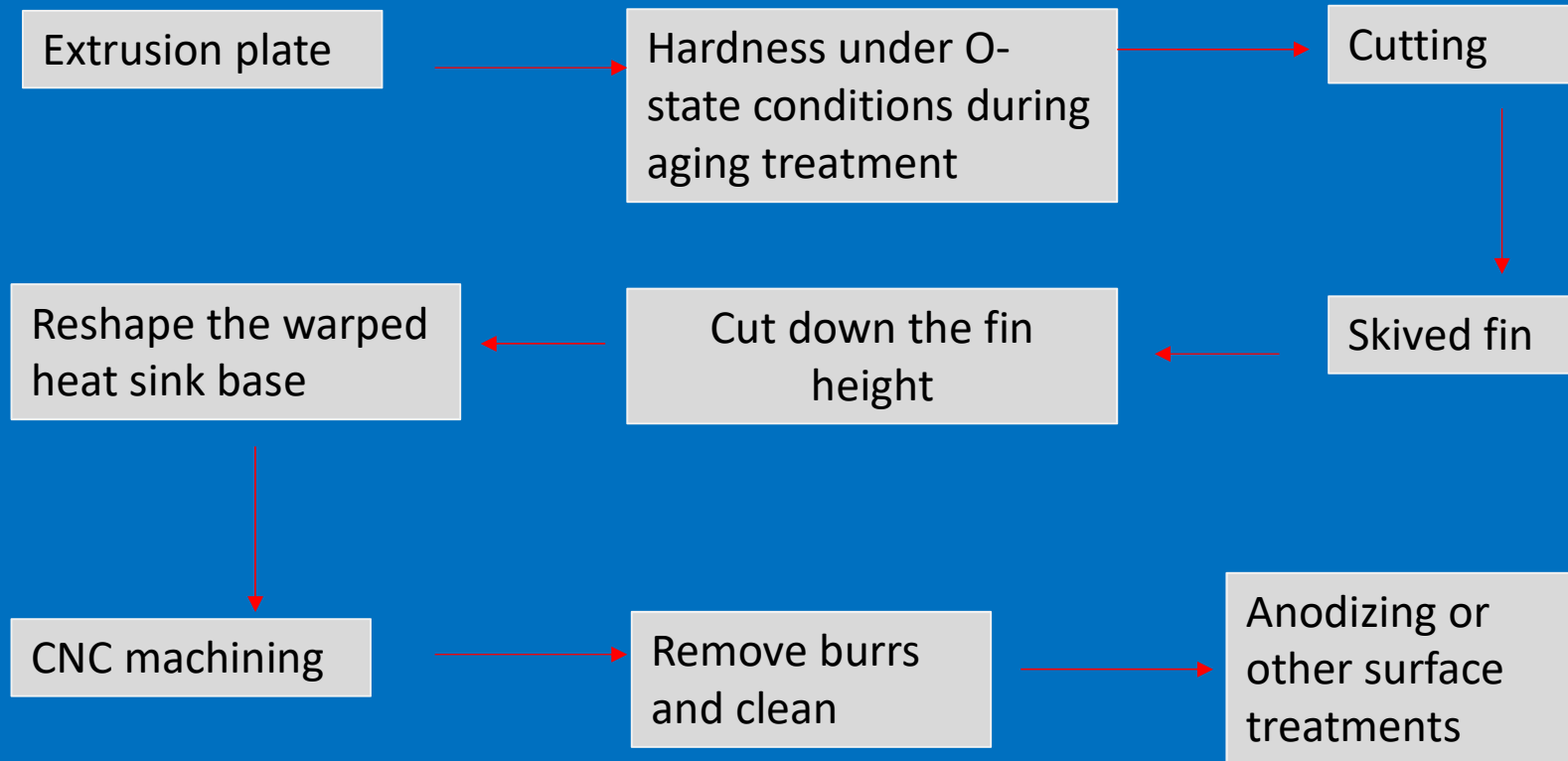
Skived fin technology

This kind of heat sink forms thin and closely arranged fins by precisely skiving metal materials such as aluminum or copper. These fins can increase the surface area. During the heat conduction process, heat can be dissipated from the heat source to the surrounding air more quickly, effectively reducing the temperature of the object and is widely used in the field of heat dissipation for electronic devices.



Skived fin technology

-Process Sequence



Skived fin technology

-Processing parameters

Machin able materials: AL 1060,Al 6063-T4,Copper C1100;

Maximum processing width: 700mm with 1.5mm fin thickness (Aluminum);

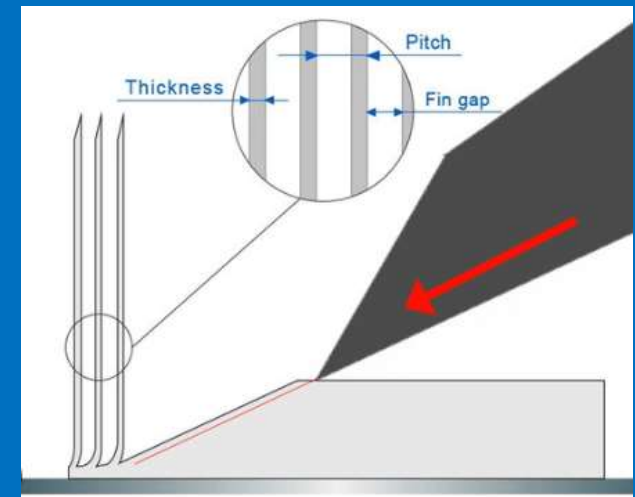
Maximum processing Height: 120mm with 1.8mm fin thickness (Aluminum);

Max fin thickness: 1.0mm (C1100); 2.0mm (Aluminum);

Max fin gap: 5.5 times the thickness of the fin (Aluminum);

Minimum fin thickness: 0.05mm (C1100); 0.5mm (Aluminum);

Minimum fin gap : 0.05mm (C1100); 0.5mm (Aluminum);



Skived fin technology

-Why use?

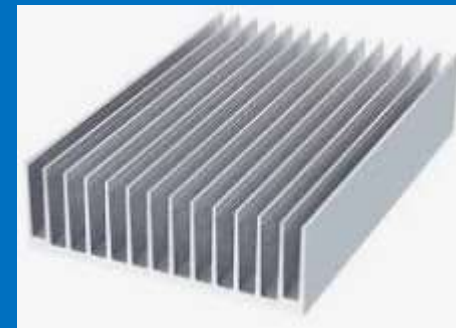
- Replace extrusion technology
- Replace epoxy bonding process
- Replace brazing process
- The demand for high-power cooling, high-density fin heat sinks
- Low cost mold
- Higher cost than profile process heat sink.



Epoxy bonding



Brazing



Extrusion

Skived fin technology

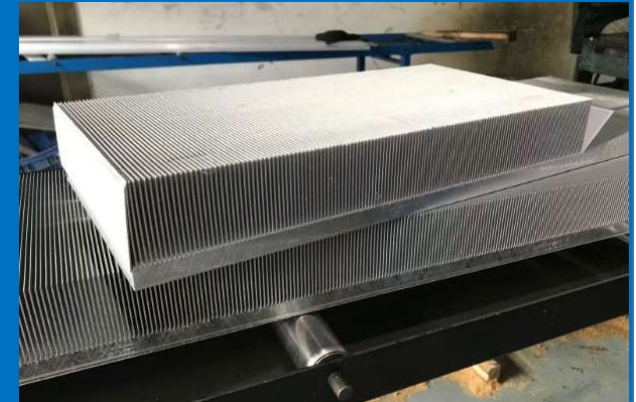
-Application?



laser equipment



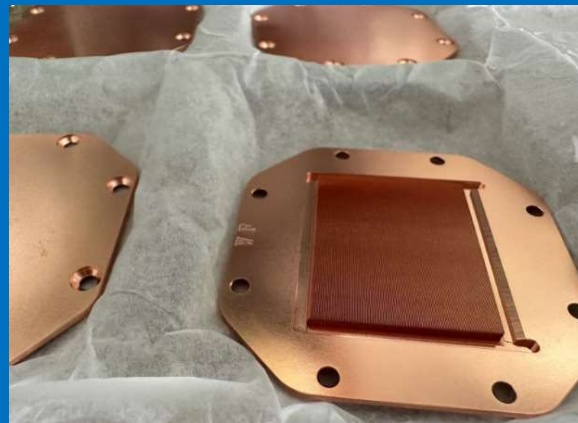
PV Inverter



IGBT



Medical Equipment



AI Server Computing



Automotive PTC heating
tube

KINGKA

Thanks!